Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π--MOSV)

## 2SK2777

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : R_{DS} \ (\text{ON}) = 0.9 \ \Omega \ (\text{typ.}) \\ \bullet & \text{High forward transfer admittance} & : |Y_{fs}| = 5.5 \ S \ (\text{typ.}) \\ \bullet & \text{Low leakage current} & : I_{DSS} = 100 \ \mu\text{A} \ (\text{max}) \ (\text{V}_{DS} = 600 \ \text{V}) \\ \bullet & \text{Enhancement-mode} & : V_{th} = 2.0 \sim 4.0 \ V \ (\text{V}_{DS} = 10 \ \text{V}, I_{D} = 1 \ \text{mA}) \\ \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		$V_{DGR}$	600	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	Α	
	Pulse (Note 1)	$I_{DP}$	24	Α	
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	65	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	345	mJ	
Avalanche current		I <sub>AR</sub>	6	Α	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	6.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.92	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

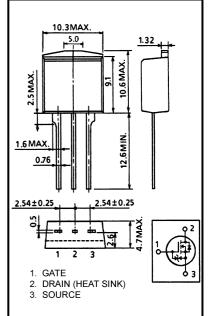
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 16.8 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 6 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

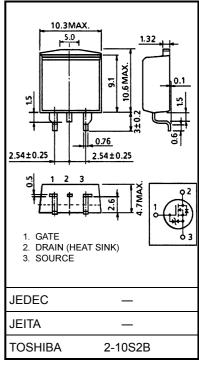
Please handle with caution.



2-10S1B

Weight: 1.5 g (typ.)

JEDEC JEITA TOSHIBA



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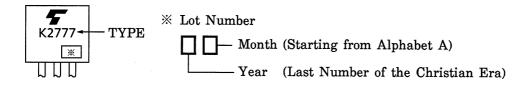
## **Electrical Characteristics (Ta = 25°C)**

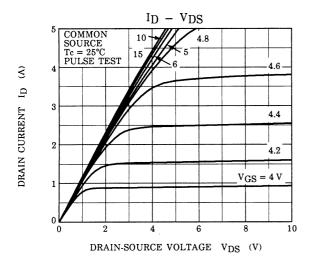
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V <sub>(BR)</sub> GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	-	-	V
Drain cut-off cui	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold v	voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A	_	0.9	1.25	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	2.0	5.5	_	S
Input capacitano	e	C <sub>iss</sub>		_	1300	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		C <sub>oss</sub>		_	400	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OUT}$ $V_{OUT}$ $V_{DD}$ $V_{OUT}$ $V_{DD}$	_	25	_	
	Turn-on time	t <sub>on</sub>		_	45	_	20
	Fall time	t <sub>f</sub>		_	40	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$	_	150	_	
Total gate charge (gate-source plus gate-drain)		Qg			30	_	
Gate-source charge		$Q_{gs}$	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$		_	12	_	

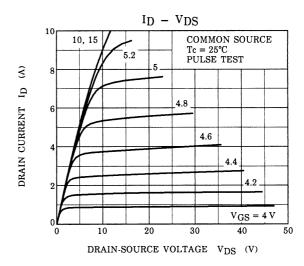
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

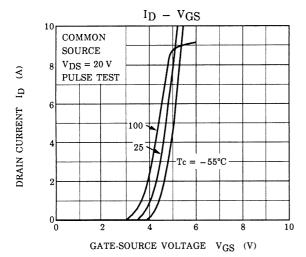
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	6	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	24	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}, dI_{DR} / dt = 100 \text{ A} / \mu \text{s}$		1000		ns
Reverse recovery charge	Q <sub>rr</sub>		_	7	_	μC

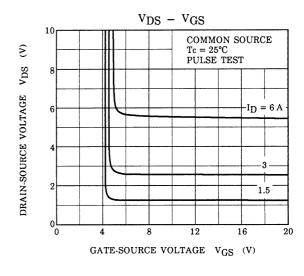
## Marking

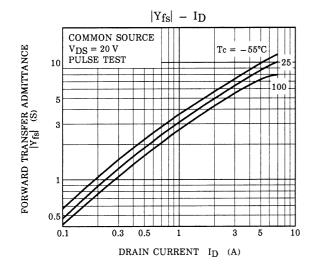


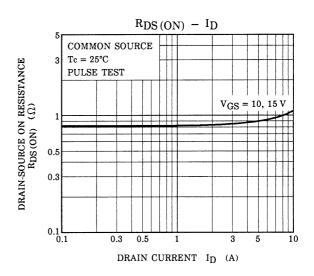


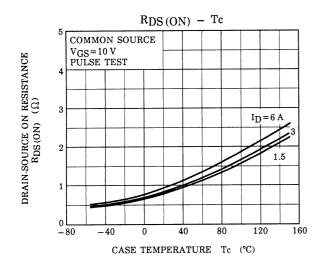


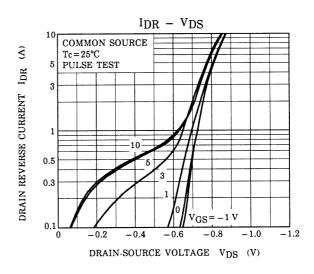


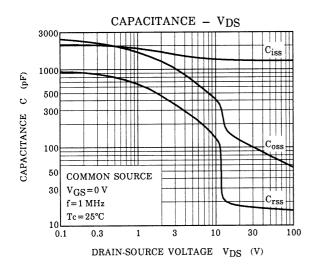


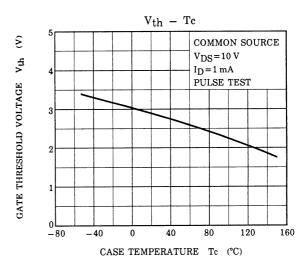


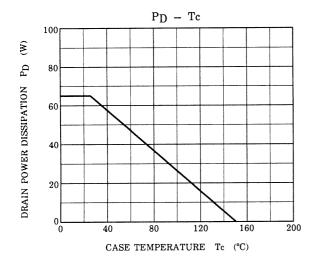


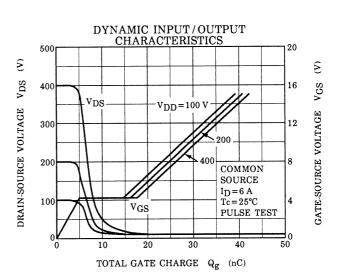


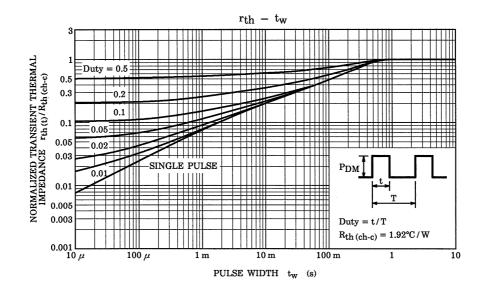


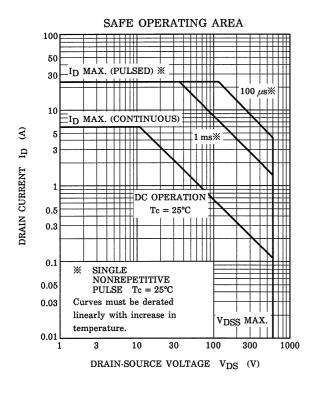


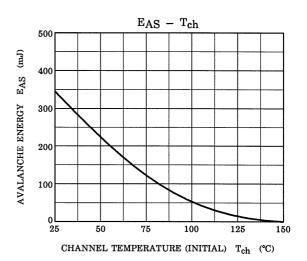


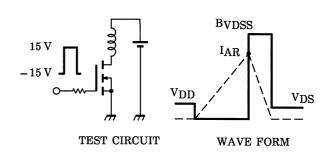












$$R_G = 25 \Omega$$
  
 $V_{DD} = 90 \text{ V, L} = 16.8 \text{ mH}$ 

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$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

#### **RESTRICTIONS ON PRODUCT USE**

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